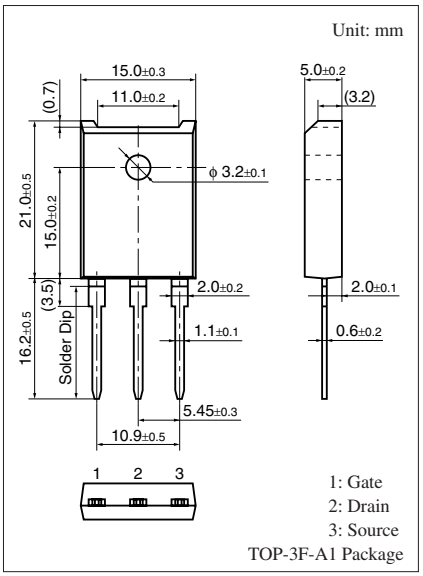
2SK3318

Silicon N-channel power MOSFET

For switching



■ Features

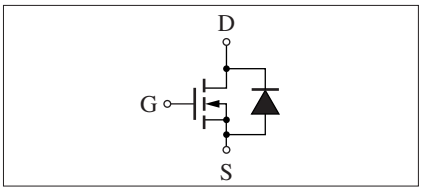
- Avalanche energy capability guaranteed
- High-speed switching
- Low ON resistance R_{on}
- No secondary breakdown

■ Absolute Maximum Ratings $T_C = 25°C$

Parameter		Symbol	Rating	Unit
Drain-source surrender voltage		V_{DSS}	600	V
Gate-source surrender voltage		V_{GSS}	±30	V
Drain current		I_D	±15	A
Peak drain current		I_{DP}	±60	A
Avalanche energy capability *		EAS	112.5	mJ
Power dissipation		P_D	100	W
	$T_a = 25°C$		3	
Channel temperature		T_{ch}	150	°C
Storage temperature		T_{stg}	−55 to +150	°C

Note) *: L = 1 mH, I_L = 15 A, 1 pulse

Internal Connection

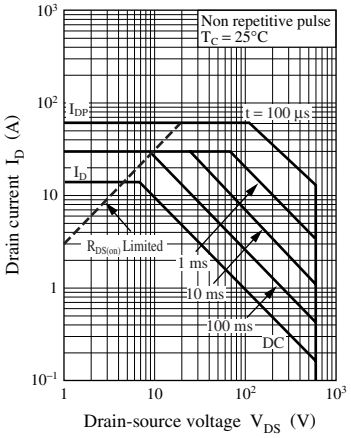


■ Electrical Characteristics $T_C = 25°C \pm 3°C$

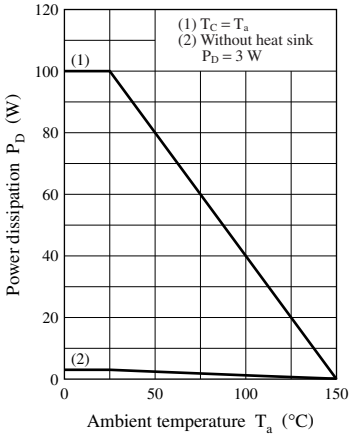
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Gate-drain surrender voltage	V_{DSS}	I_D = 1 mA, V_{GS} = 0	600			V
Diode forward voltage	V_{DSF}	I_{DR} = 15 A, V_{GS} = 0			−1.5	V
Gate threshold voltage	V_{th}	V_{DS} = 25 V, I_D = 1 mA	2		4	V
Drain-source cutoff current	I_{DSS}	V_{DS} = 480 V, V_{GS} = 0			10	μA
Gate-source cutoff currentt	I_{GSS}	V_{GS} = ±30 V, V_{DS} = 0			±1	μA
Drain-source on resistance	$R_{DS(on)}$	V_{GS} = 10 V, I_D = 7.5 A		0.33	0.46	Ω
Forward transfer admittance	$\|Y_{fs}\|$	V_{DS} = 25 V, I_D = 7.5 A	6	10		S
Short-circuit forward transfer capacitance (Common-source)	C_{iss}	V_{DS} = 20 V, V_{GS} = 0, f = 1 MHz		3 500		pF
Short-circuit output capacitance (Common-source)	C_{oss}			340		pF
Reverse transfer capacitance (Common-source)	C_{rss}			50		pF
Turn-on delay time	$t_{d(on)}$	V_{DD} = 150 V, I_D = 7.5 A		40		ns
Rise time	t_r	R_L = 20 Ω, V_{GS} = 10 V		55		ns
Turn-off delay time	$t_{d(off)}$			310		ns
Fall time	t_f			70		ns
Channel-case heat resistance	$R_{th(ch-c)}$				1.25	°C/W
Channel-atmosphere heat resistance	$R_{th(ch-a)}$				41.7	°C/W

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

Safe operation area



P_D — T_a



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